502959040 09/02/2014

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHAN-HONG CHERN	02/15/2011
FU-LUNG HSUEH	02/24/2011

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14475058

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	09/02/2014

Total Attachments: 2

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PATENT 502959040 REEL: 033652 FRAME: 0604

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid	l, the receipt and sufficiency of
which is hereby acknowledged, the undersigned,	
1) Chan-Hong CHERN	
2) Fu-Lung HSUEH	
who has made a certain new and useful invention, hereby sells, assigns and transfers unto	
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. ha	ving a place of business at
No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.	
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for as defined in 35 U.S.C. 100 in the invention entitled	or the United States of America
INTEGRATED CIRCUITS WITH RESISTORS AND METHODS OF FOR	MING THE SAME
(a) for which an application for United States Letters Patent was filed on 2-25-2011 States Patent Application No. 13/035, 533; or	_, and identified by United
(b) for which an application for United States Letters Patent was executed on,	
and the undersigned hereby authorizes and requests the United States Commissioner of Patents an all United States Letters Patent which may be granted therefore and any and all extensions, divisi continuations-in-part thereof, and the right to all benefits under the International Convention for Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal reagrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNE	ons, reissues, continuations, or or the Protection of Industrial epresentatives; the undersigned
AND the undersigned hereby agrees to transfer a like interest, and to render all ne application for and obtaining original, divisional, reissued or extended Letters Patent of the United ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in applications for patent based thereon, growing out of or related to the said invention; and to ex ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's furthe invention hereby transferred.	States, upon request of the said and to any improvements, and recute any papers by the said
SIGNED on the date indicated aside my signature;	
	/
2/15/201	<u></u>
Name: Chan-Hong CHERN Date:	
2)	
Name: Fu-Lung HSUEH Date:	· · ·

PATENT REEL: 033652 FRAME: 0605

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,		
1) Chan-Hong CHERN		
2) Fu-Lung HSUEH		
who has made a certain new and useful invention, hereby sells, assigns and transfers unto		
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD, having a place of business at		
No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.		
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled		
INTEGRATED CIRCUITS WITH RESISTORS AND METHODS OF FORMING THE SAME		
(a) for which an application for United States Letters Patent was filed on 2-25-11. and identified by United States Patent Application No. 13/035, 533; or		
(b) for which an application for United States Letters Patent was executed on,		
and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;		
AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.		
SIGNED on the date indicated aside my signature:		
• -		
1)		

PATENT REEL: 033652 FRAME: 0606

RECORDED: 09/02/2014